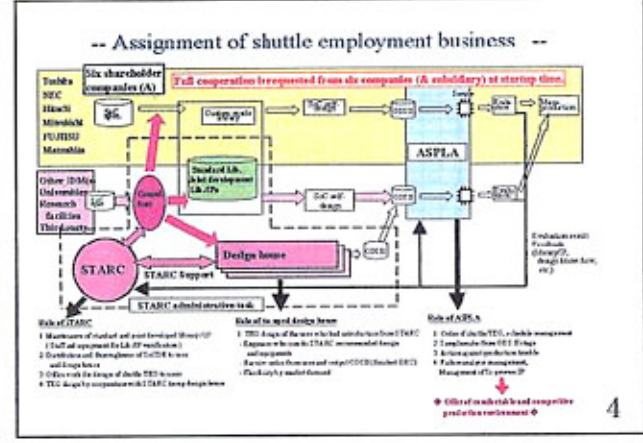
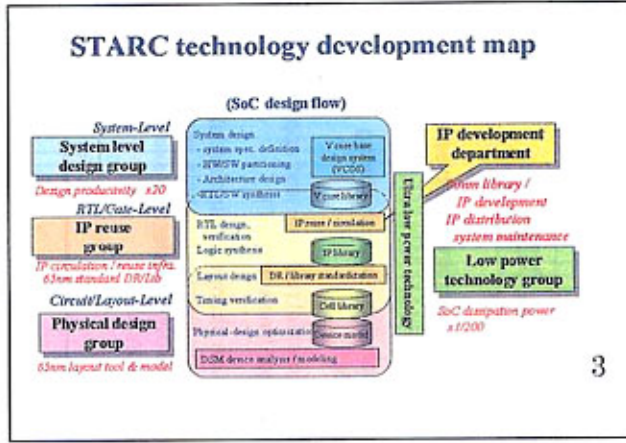
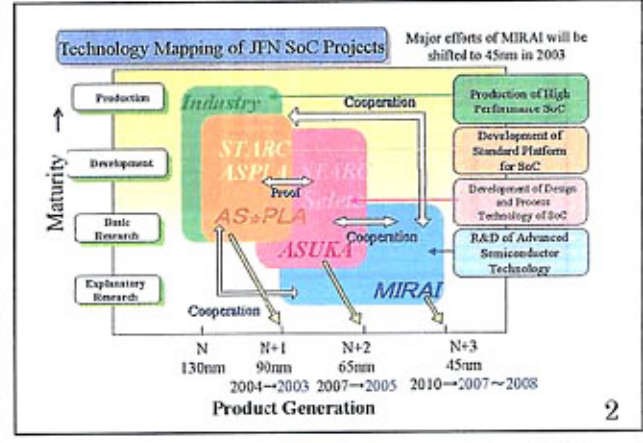
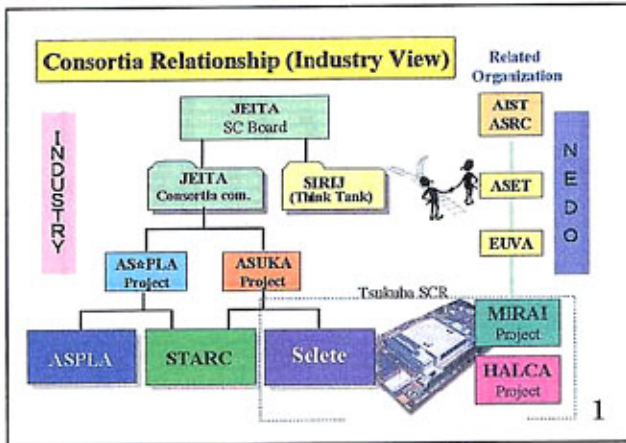


Strategic Directions of Semiconductor Consortia and Expectation to COE Program

Semiconductor Technology Academic Research Center (STARC)
President & CEO Toyoki Takemoto

Semiconductor products have become a staple of industry, having incorporated into not only information and communication devices but a wide range of other industrial devices as well. On the other hands, competition becomes more and more severe, so semiconductor companies have to increase the speed of selection and focus, and promote rapid standardization as an industry. Therefore, a lot of Japanese consortia are founded to contribute to help making standardization and decrease the duplicated investment.

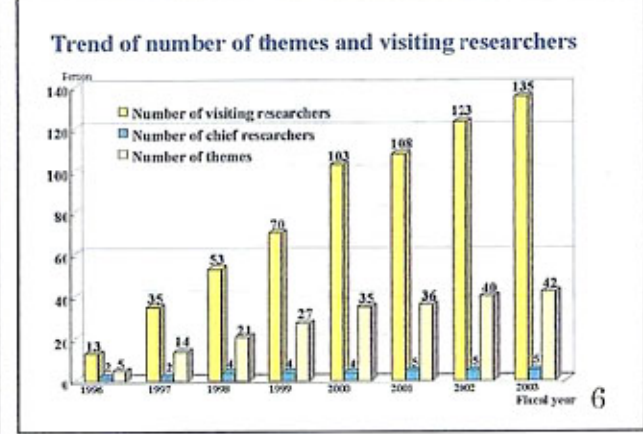
First of all, I explain the activities of Japanese consortia including STARC and next, I discuss examples of the cooperation of industry and academia. Lastly, I touch upon the expectation to the 21st century COE.



Feature of STARC Design Course

- Reform lecture text
 - Establish embedded SW design course, create three courses text in 2002.
- Develop three training course
 - Training of simple AV playback system in DVD system.
 - LSI design course .. Done
 - Embedded SW design / System design course .. Done
- Start advanced lecture course
 - IP reuse design (volume on SoLID) .. done

Training equipments of DVD system and training scenery in LSI design course



Strategic Directions of Semiconductor Consortia and Expectation to COE Program

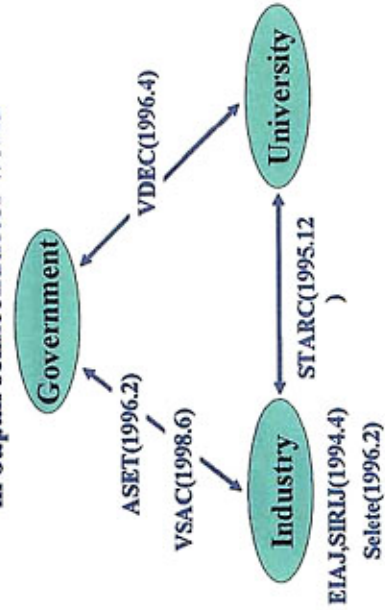
Toyoki Takemoto
President & CEO
STARC
March 17, 2003

Outline

1. Semiconductor Consortia
2. Technology Trend
3. STARC Activities
4. Activity-1
Strengthening of SoC Design Power
5. Activity-2
Research Support and Activation in Universities
6. Expectation to the "COE"

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Industry, university and government in Japan semiconductor world



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Semiconductor Industry Players

Industry

Chip Makers
 NEC, Toshiba, Hitachi, Fujitsu, Mitsubishi, Matsushita, Sony, Sharp, Sanyo, Rohm, Oki, (Elpida, Trecenti, RENESAS)...

Equipment Suppliers
 TEL, Nikon, Canon, Accretech, DNS, Advantest, ULVAC,...

Material/Mask Suppliers
 TOK, JSR, Shinetsu, MS Silicon, Hoya, DNP, Toppan....

Trade Associations
 JEITA: Chip Makers, Electronics Equipment and Component Manufacturers
 SEAJ: Equipment and Material Suppliers

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Academia / National Labs

Universities
 Tohoku, Tokyo, Osaka, Hiroshima,

National Labs (AIST)
 Advanced Semiconductor Research Center (ASRC)
 Nanoelectronics Research Institute (NeRI)

Government
 Ministry of Economics, Trade and Industry (METI)
 New Energy and Industrial Technology Development Organization (NEDO)

COE Workshop

STARC Semiconductor Technology Academic Research Center

Semiconductor R&D Consortia in Japan

STARC: Semiconductor Technology Academic Research Center

Selete: Semiconductor Leading Edge Technology Inc.

ASET: Association of Super-Advanced Electronic Technologies

MIRAI: Millennium Research for Advanced Information Technology (ASRC + ASET)

ASPLA: Advanced SOC Platform Corporation







EUVA: Extreme Ultraviolet Lithography System Development Association

STARC **ASET** **ASPLA** **IRAI** **EUVA**
Selete

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Major R&D Programs

ASUKA	2001-2005	
MIRAI	2001-2007	
HALCA	2001-2003	}
Electronic SI	1999-2003	
PFC Alternative	1999-2003	
EUV	1998-2006	
SOC Platform	2002-2004	 

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Selete

- Semiconductor Leading Edge Technology Inc.
- Founded Feb. 1996
- Programs
 - Advanced Lithography (VUV, Mask, EPL)
 - Advanced Process (FEP,BEP)
 - ICAD
 - ASUKA Research Line
- Members
 - Shareholders: Fujitsu, Hitachi, Matsushita, Mitsubishi, NEC, Oki, Rohm, Sanyo, Sharp, Sony, Toshiba
 - Contractors: Shareholders, Seiko Epson, Samsung

ASPM

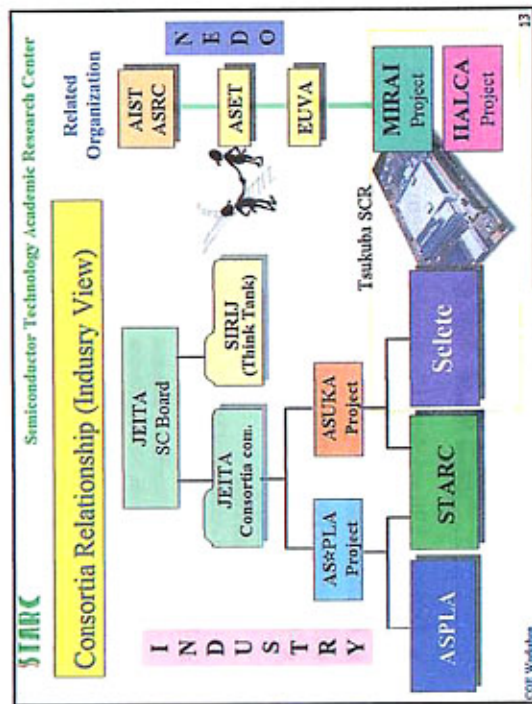
- Association of Super-Advanced Electronics Technologies
- Founded Feb. 1996
- Programs
 - PFC Substitution Process
 - Electronic System Integration
 - MIRAI (Joint project with ASRC)
 - HALCA (Highly Agile Line Concept Advancement)
- Members
 - Chip makers, Suppliers, Materials, Users...47
 - Foreign Members: Intel, Samsung, (ASSM Japan)

EUVA

- Extreme Ultraviolet Lithography System Development Association
- Founded June, 2002
- Mission :To complete an EUV prototype machine
- Programs
 - EUV light source
 - EUV exposure tool
 - Design and evaluation of EUV lithography system
- Members
 - Canon, Nikon, Gigapoton, Komatsu, Ushio, Fujitsu, Hitachi, Mitsubishi, NEC Electronics, Toshiba

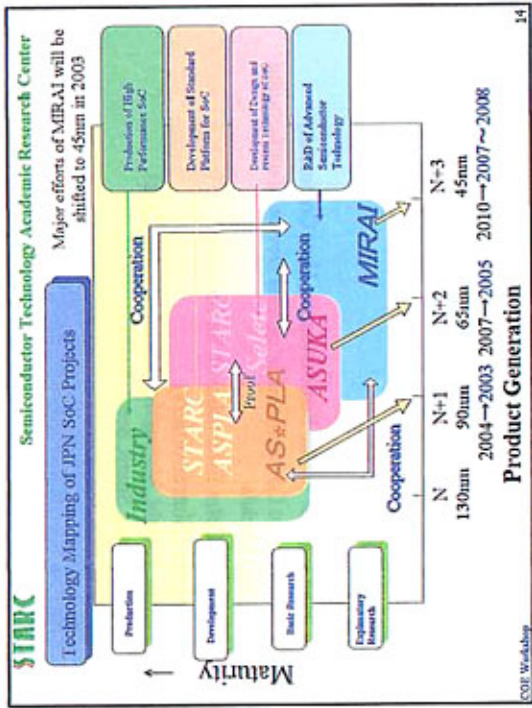
ASPLA

- Advanced SoC Platform Corporation
- Founded July 2002
- Mission
 - Best Practice for the Semiconductor User Community
 - Solution for Conventional Integrated Device Manufacturing (IDM) Models
 - SOC Platform Establishment for Industry
- Members (Shareholders)
 - Fujitsu, Hitachi, Matsushita, Mitsubishi, NEC, Oki, Rohm, Sanyo, Sharp, Sony, Toshiba



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13



COE Workshop

14

- STARC** Semiconductor Technology Academic Research Center
1. Semiconductor Consortia
 2. **Technology Trend**
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- COE Workshop

COE Workshop

15

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Research and development cost of IDM
(% for sales)

	250 nm	180 nm	130 nm	90nm
Process technology	4.6	4.7	4.8	4.9
Product technology	5.2	5.7	6.4	8.1
IP development	1.5	2.3	3.1	3.9
Software development	0.1	0.3	2.4	5.2
Development platform	0.0	0.1	0.6	1.7
Total	11.4	13.1	17.3	23.8

From ISS report

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16

Market trend of ICT era

Variation in semiconductor industry

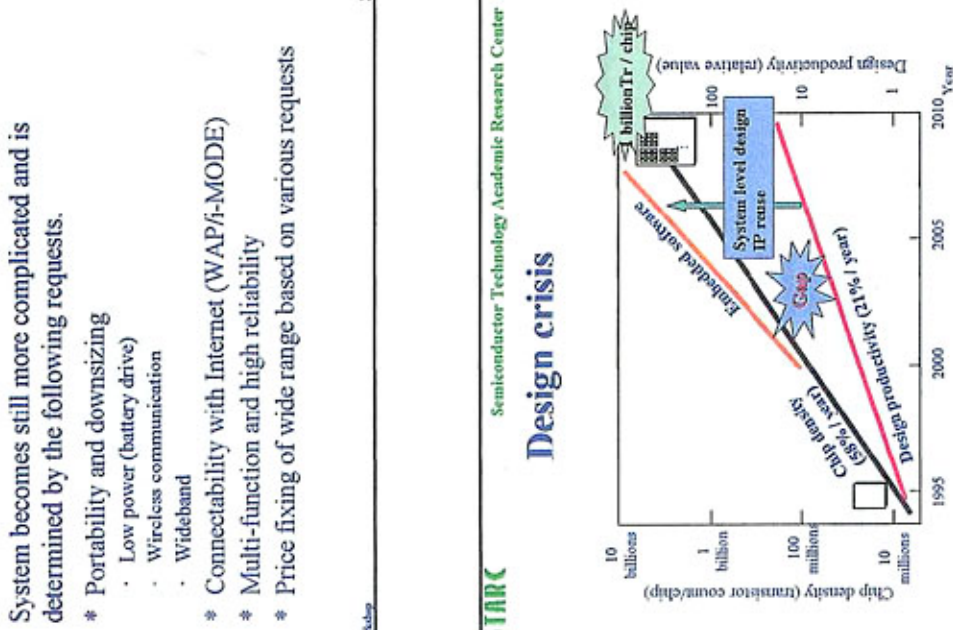
- * System becomes still more complicated and is determined by the following requests.
 - Portability and downsizing
 - Low power (battery drive)
 - Wireless communication
 - Wideband
 - * Connectivity with Internet (WAP/i-MODE)
 - * Multi-function and high reliability
 - * Price fixing of wide range based on various requests

Semiconductor technology load map

(2001 ITRS-Int'l Technology Roadmap for Semiconductors)

Item	2001	2004	2007	2010	2013	2016
DRAM half pitch	130	90	65	45	30	22
SFET half pitch	150	90	65	45	30	22
SI wafer diameter	300	300	300	300	450	450
Core insulator thickness	1.3-1.6	0.9-1.4	0.7-1.0	0.5-0.8	0.4-0.6	0.3-0.5
Supply voltage	1.2-1.1	1.2-1.0	1.1-0.7	1.0-0.6	0.9-0.5	0.9-0.4
Dielectric constant	3.0-3.6	2.6-3.1	2.3-2.7	2.0-2.5	1.9-2.2	2.1
Wire pitch	7	8	9	9-10	9-10	10
DRAM Access time (fast product)	200(250)	40(10)	160(40)	220(80)	400(210)	640(840)
No. of Trs. (64C)	193	386	779	1546	3091	6184
Tr. Density (64C)	38.6	77.2	154.3	309	617	1234
Clock frequency	GB	4.0	6.7	11.5	19.3	28.3
Power (1P-3P)	1.4-1.9	3.2-1.6	3.5-1.9	3.0-2.8	3.0-2.1	3.0-2.8
Design labor. (64C)	10	22	11	11	11	11

Design crisis



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Business of STARC

1. Strengthening of SoC Design Power!

Purpose: Improvement of SoC design productivity

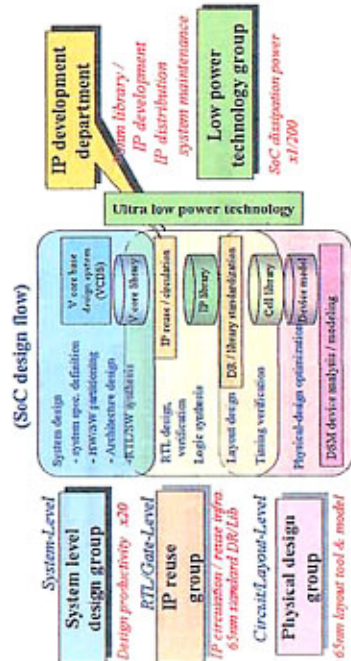
- (1) SoC design environmental development
 - system level design automation
 - physical design optimization
- (2) IP (Intellectual property)
 - IP reuse / circulation
 - low power IP
- (3) Acceleration of 90nm library and IP development
 - Cooperation with ASPLA

2. Research Support and Activation in Universities

- (1) STARC / universities joint research
- (2) SoC designer education (students & engineers)

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STARC technology development map



Missions of Physical Design Group

- Development of optimization technology of circuit and layout design accompanying scaling
- Verification of physical and electromagnetic phenomena by using TEG
 - Wiring delay, cross talk, inductance, fluctuation
 - Substrate noise, reliability (electro-migration)
- High precision simulation model of scaled elements
 - LCR extraction, analysis, HiSIM model
- Introduction and benchmark to layout EDA tools

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Outline of STARC-TEG02

- IP-Process/Diagnostic TEG
- IP-Process/Diagnostic TEG
- IP-Process/Diagnostic TEG
- IP-Process/Diagnostic TEG
- IP-Process/Diagnostic TEG

- IP-Process/Diagnostic TEG
- IP-Process/Diagnostic TEG
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- IP-Process/Diagnostic TEG

Chip size: 20.5x20.5 mm² (535mm² x 16)

90 nm ASPLA-DRAM

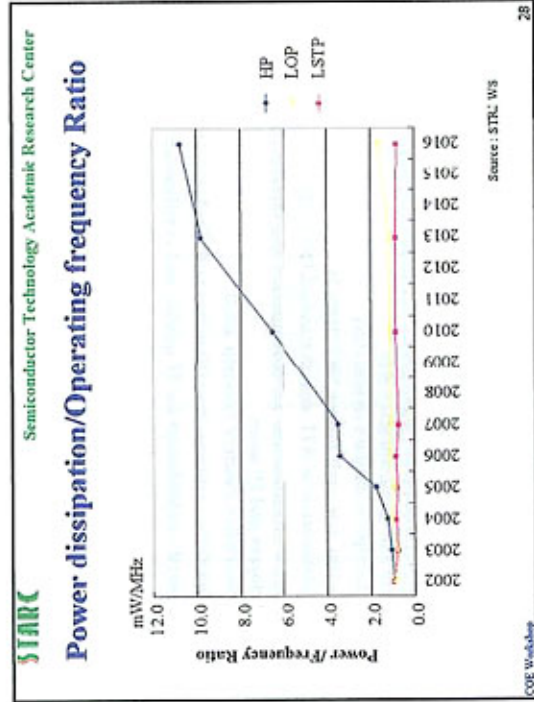
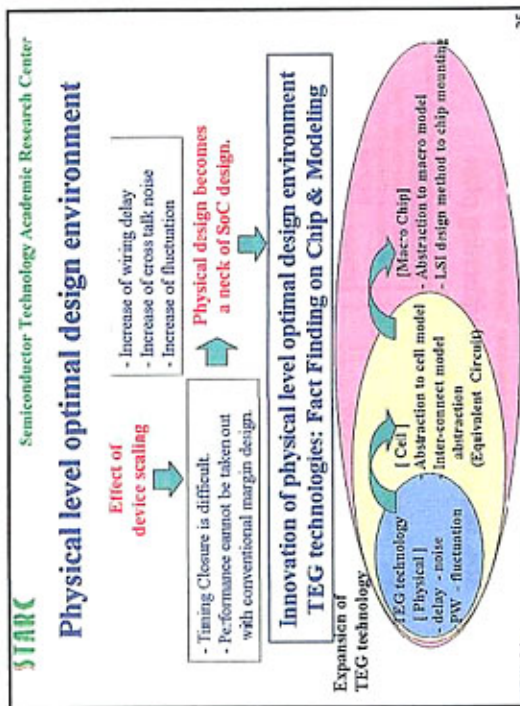
Contents

- process, device evaluation TEG
- fluctuation and yield design
- signal integrity design TEG
- HSIM parameter extraction
- SI model DB
- New wiring architecture / circuit actual proof
- EDA performance benchmark
- Others
- SRAM-TEG
- IP Process Diagnostic TEG
- WLR (Water Level, Reliability)-TEG

Schedule

- 2002.12 Tape out (N)
- 2003.04 Wafer up (N)
- 2003.06 Report

26



- STARC** Semiconductor Technology Academic Research Center
- ### Missions of Low Power Technology Group
- Development of low power technology of SoC
 - Low power technologies in architecture and circuit level aim at the present condition ratios 1/200
 - System (CPU) low power technology
 - ◆ Low voltage circuit technology of 0.5V
 - ◆ Power control optimization technology
 - Embedded analog technology
 - ◆ 1V operation ADC
 - ◆ Analog digital mixed noise technology
 - On-chip RAM technology
 - ◆ 0.5V operation on chip RAM
- 27

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STARC
Missions of IP Reuse Group

- **Development of IP reuse / circulation technology**
 - Establishment of criteria, such as IP description and quality
 - Actual proof experiment of IP circulation infrastructure
 - Establishment of recommended DR (design rule) usage technology
 - Development of 65nm common DR / libraries
 - Spread activities of IP related standardization

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STARC
Infrastructure technology of IP reuse and circulation
About recommended IP criteria (description, quality)

1. Technical standards establishment for promoting coordination of system and semiconductor side
 - IP description standard (syntax side)
 - Design style guide version 2002 (2002. 2)
 - Establishment of RTL sign-off standard (2001. 12)
2. Standard establishment for coordination and understanding of IP developers and IP users
 - IP description standard (semantic side)
 - Functional / synthesis description standard (draft) (2002. 3)
3. Standard establishment for IP quality and certification
 - IP quality standard (objective criterion of quality measurement)
 - Design property quality certification standard/scoring tool (2001. 12)
4. IT system standard establishment for IP information distribution
 - IP information acquirment by easy, safety, cheap way
 - IP exchange interface standard (2002. 3)

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STARC
SoC design power strengthening plan
- IP market creation -

Key of market activation
 (1) Effective highly functional IP
 (2) Easy procurement of reliable IP from market
 (3) Profitable mechanism by supplied IP into market

[Ment of industrial world]
 (1) Expansion and activation of SoC market
 - Everyone designs SoC easily -
 (2) Improvement of SoC design productivity
 (3) Increment in SoC production flexibility
 (4) Common basic technologies
 - Strategic concentration of resource, Change of business model -

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STARC
Assignment of shuttle employment business --

Role of STARC
 1. Measure of financial strategy and technology IP
(Draft and experiment for Lib. IP realization)
 2. Distribution and management of SoC DR in use
 3. DR development and type SoC DR (based on SoC)
 4. TSS development by cooperation with STARC level design house

Role of ASPLA
 1. Core intellectual, technical measurement
 2. Support realization (SoC DR map)
 3. Actual SoC DR realization
 4. Market development support
 Management of IP reuse

Role of Design house
 1. TSS development and type SoC DR (based on SoC)
 2. Actual SoC DR realization
 3. Market development support
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Role of STARC administrative task
 1. TSS development and type SoC DR (based on SoC)
 2. Actual SoC DR realization
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 Management of IP reuse

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SoC Design Engineer Education Scheme



SoC Design Course (contribution, support, cooperation)

- Waseda University, Graduate school, Science and Engineering
- Keio University, Graduate school, Science and Technology
- Oita University, Graduate school, Faculty of Engineering
- Osaka University, Graduate School of Engineering Science
- Tokyo Institute of Technology, Graduate School of Engineering
- Ritsumeikan University, Institute of Science and Engineering
- Nagoya University, Graduate School of Engineering
- Kyoto University, Graduate School of Informatics
- Shizuoka University, Graduate school, Faculty of Information

Feature of STARC Design Course

- Reform design text
 - Establish embedded SW design course, create three kind of course text in 2002.
- Develop three training course
 - Training of simple AV playback system in DVD system.
 - LSI design course .. Done
 - Embedded SW design / System design course .. Done
- Start advanced seminar course.
 - IP reuse design (volume on SoLID) .. done



Training equipments of DVD system and training scenery in LSI design course.

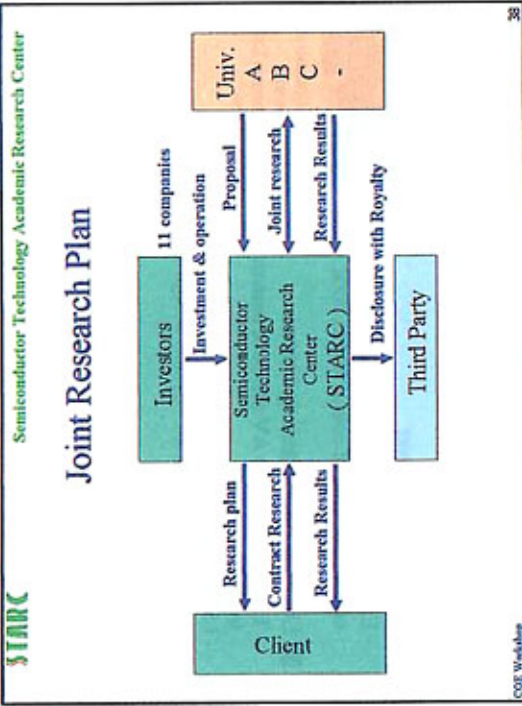
Joint Research with Universities in STARC

Basic approach with regard to joint research themes :

- 1) Research and development of new technologies that will become industry standards or the mainstream in a particular industry in the future.
- 2) Pre-competitive R&D relating to technologies that will be transferred to the industrial sector 5-10 years in the future.
- 3) R&D that will tie into education of young researchers who will contribute to the future of the industrial sector.
- 4) Target technology roadmap.
<http://www.star.c.jp/roadmap/>

37

COE Workshop



38

COE Workshop

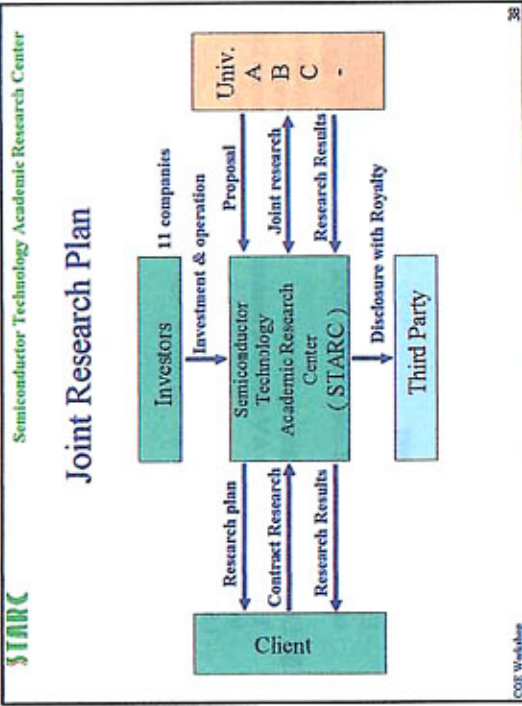
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<http://www.star.c.jp/roadmap/>

37

COE Workshop



38

COE Workshop

STARC supports academic research

- 1) In the field of Si LSI
- 2) Valuable and transferable to the industries within 10 years
- 3) 3 to 5 years project
- 4) Funding : 15 - 20 million yen / year for PG
 5 - 10 million yen / year for PJ
- 5) STARC provides industry needs and information through Visiting Researchers from member companies.

39

COE Workshop

STARCC Semiconductor Technology Academic Research Center

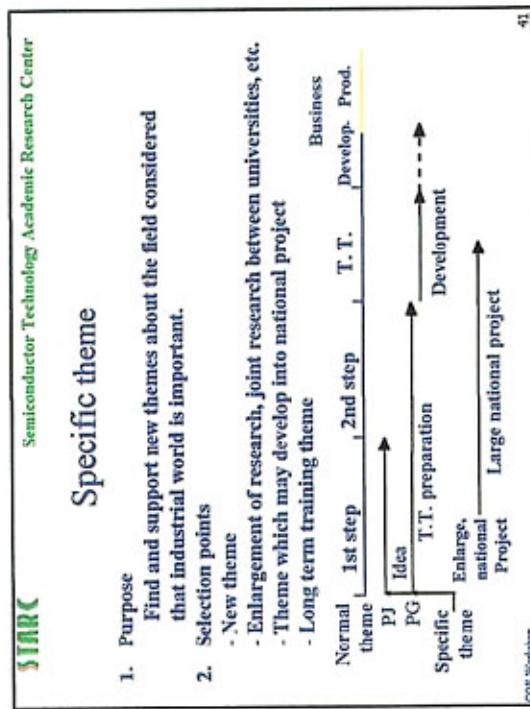
Trend of university researchers

Year	Prof. Ass't	Asst. Prof.	Master	Bachelor	Other	Total
1996	8	12	8	11	0	51
1997	25	20	28	40	0	137
1998	38	20	34	67	4	198
1999	50	26	48	95	44	272
2000	65	36	57	133	66	373
2001	59	30	48	118	44	315
2002	81	38	50	147	38	370

Position Sequence

Year	Ph.D. Comp.	Other Comp.	University	Process No.	Total
1999	14	14	4	30	62
2000	26	25	6	70	127
2001	34	28	9	45	116
2002	45	31	5	62	143

COE Workshop 42



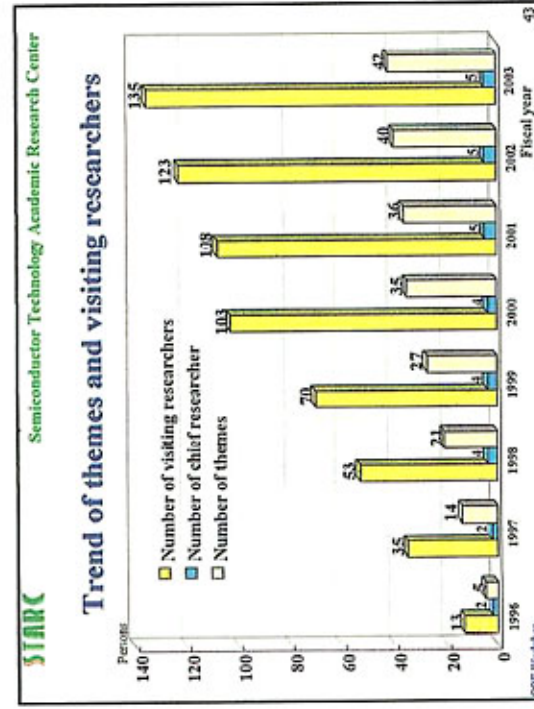
STARCC Semiconductor Technology Academic Research Center

Research Program and Projects in 2003 (42 themes)

Area	Research representatives
Architecture	Amara (Keio U.), Kasahara (Waseda U.), Marjima (T.I.T.), Matsunouchi (Hiroshima U.), Miyazawa (Hokkaido U.), Murakami (Osaka U.), Shibahara (U. of Tsukuba), Sakai (U. of Tokyo), Soryuzaki (Kumamoto U.), Sugino (T.I.T.), Yoshizato (Kanazawa U.)
LSI circuit	Hyogo (Science U. of Tokyo), Iwata (Hiroshima U.), Kawahito (Shizuoka U.), Kobayashi (Gama U.), Kunoda (Keio U.), Taniguchi (Osaka U.)
Design technology	Asada (U. of Tokyo), Fujita (U. of Tokyo), Fujiwara (NIST), Homaguchi (Osaka U.), Higashino (Osaka U.), Inai (Osaka U.), Iwasaki (TMU), Nakajima (TUT), Sakurai (U. of Tokyo), Takamatsu (Ehime U.), Terai (Ritsumeikan U.)
Device	Miura (Hiroshima U.), Ogawa (Kobe U.), Okuyama (Osaka U.), Shibahara (Hiroshima U.), Taniguchi (Osaka U.), Toriumi (U. of Tokyo), Kamidano (U. of Tsukuba)
Process	Hanaguchi (Kyoto U.), Keike (Tohoku U.), Masu (T.I.T.), Saitoh (Tohoku U.)
Common	Iwai (T.I.T.), Koyanagi (Tohoku U.), Oshima (U. of Tokyo)

System 28 Process 14

COE Workshop 44



Joint Research with Hiroshima University and STARC

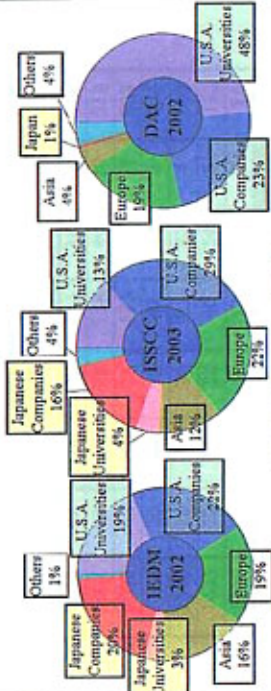
1. Prof. Iwata "Analog Digital Mixed Circuit" (1996)
"Low Voltage Analog Circuit Design for Low Noise Systems" (2003)
2. Prof. Miura "Research on Predictive TCAD for Concurrent Engineering" (1998)
"HISIM: A MOSFET Model for Circuit Simulation with Focus on RF Applications" (2002)
3. Prof. Matsumura "Super-Compact Multi-Port Memories with Large Random-Access Bandwidth and their Application for High-Performance Systems on a Chip/Package" (2001)
4. Prof. Shibahara "Research on the Gate Stack Structures with Dual-Metal and ALD Insulator for Advanced CMOS Technologies" (2001)

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Role of Engineering Sector in University

	U.S.A	Japan
1920s	Europe University Concept Established Bell Laboratories	Europe University Concept
1940s	Success of company research Establishment of research center of company	
1970s	Retreat from company research Utilization research to a university	Company founds research center. Campus dispute
1980s	SRC starts activity. (1982) Utilization research in universities SEMATECH establishment (1987) MARCO starts activity (1998)	STARC starts activity. (1996)
2000s		Retreat from company research University tackles industry-university cooperation.

Comparison of papers in IEDM and ISSCC and DAC



Expectation to the "COE"

1. **The Pioneer Role to Silicon Technology**
Leading-edge researches and information dispatch in pre-competitive area.
2. **Cultivation of researchers with "Double Major" area of Investigation - Fusion and Diversity**
Talented researchers who could expand his research area to boundary and different domain strategically.
3. **Projects proposed by active young researchers**
-- STARC anticipates those proposals. --